

July 1990

**Single/Dual/Quad Low Power Operational Amplifiers**
**Features**

- Low Supply Current ..... <200 $\mu$ A/Amplifier
- Dual Supply Voltage Range ..... ±1.5V to ±15V
- Single Supply Voltage Range ..... 3V to 30V
- High Slew Rate ..... 6V/ $\mu$ s
- Low V<sub>OS</sub> Drift ..... 3 $\mu$ V/°C
- Low Noise ..... 15nV/ $\sqrt{Hz}$
- Dielectric Isolation

**Applications**

- Portable Instruments
- Meter Amplifiers
- Telephone Headsets
- Microphone Amplifiers
- Remote Sensors Transmitter
- Battery Powered Equipment
- For Further Design Ideas See Application Note 544

**Description**

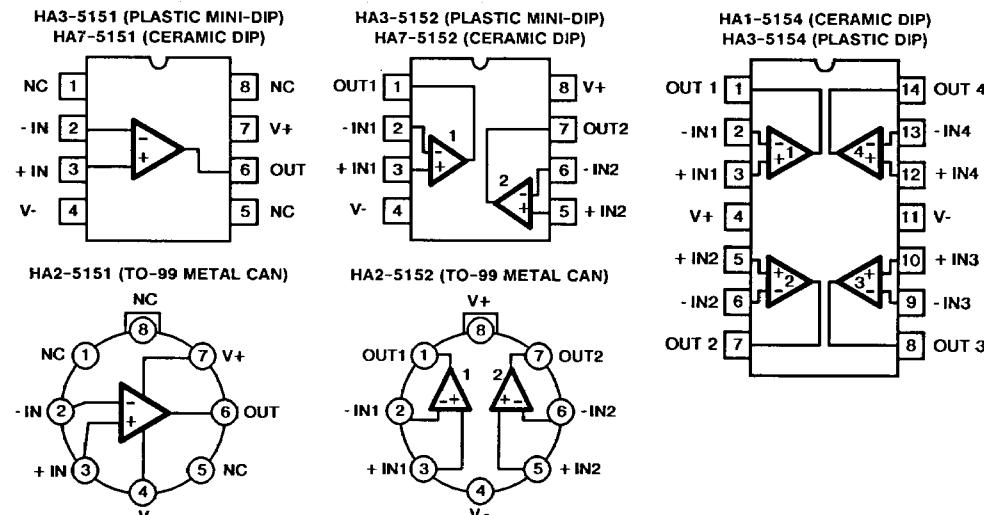
The HA-5151/52/54 series is a group of dielectrically isolated bipolar amplifiers designed to provide excellent AC performance while drawing less than 200 $\mu$ A of supply current per amplifier. These unity gain stable amplifiers are especially well suited for portable and lightweight equipment where available power is limited.

The HA-5151/52/54 series combines superior low power AC performance with DC precision not usually found in general purpose amplifiers. The DC performance is centered around low input offset voltage (0.5mV), low offset voltage drift (3 $\mu$ V/°C), and low input bias current (70nA). This is combined with a very low input noise voltage of 15nV/ $\sqrt{Hz}$  at 1kHz.

The AC performance of the HA-5151/52/54 series surpasses that of typical low power amplifiers with 6V/ $\mu$ s slew rate and a full power bandwidth of 95kHz. This makes

the HA-5151/52/54 series an excellent choice for virtually all audio processing applications as well as remote sensor/transmitter designs requiring both low power and high speed. The suitability of the HA-5151/52/54 series for remote and low power operation is further enhanced by the wide range of supply voltages (±1.5V to ±15V) as well as single supply operation (3V to 30V). These parts are also tested and guaranteed at both ±15 and single ended +5V supplies.

These amplifiers are available in singles (HA-5151, Can or Mini-DIP), duals (HA-5152, Can or Mini-DIP) or quads (HA-5154, 14 pin DIP), as well as over both the commercial (0°C to +75°C) and military (-55°C to +125°C) temperature ranges. These amplifiers also carry industry standard pinouts which allow the HA-5151/52/54's to be interchangeable with most other operational amplifiers. For military grade product refer to the HA-5151, 5152, 5154/883 data sheets.

**Pinouts**


CAUTION: These devices are sensitive to electrostatic discharge. Proper IC handling procedures should be followed.

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# Specifications HA-5151/52/54

## Absolute Maximum Ratings (Note 1)

Voltage Between V+ and V- Terminals .....	35V	HA-5151/52/54-5 .....	$0^{\circ}\text{C} \leq T_A \leq +75^{\circ}\text{C}$
Differential Input Voltage.....	$\pm 7\text{V}$	HA-5151/52/54-2 .....	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
Output Current .....	S/C Protected	Storage Temperature Range .....	$-65^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$
Internal Power Dissipation .....	500mW	Maximum Junction Temperature.....	$+175^{\circ}\text{C}$

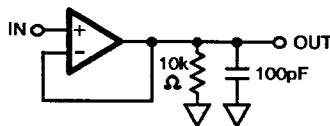
## Electrical Specifications $R_S = 100\Omega$ , $C_L \leq 10\text{pF}$ Unless Otherwise Specified.

PARAMETER	TEMP	$V_+ = +5\text{V}, V_- = 0\text{V}$			$V_+ = +15\text{V}, V_- = -15\text{V}$			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>INPUT CHARACTERISTICS</b>								
Offset Voltage	+25°C	-	0.5	3	-	0.5	3	mV
	Full	-	-	4	-	-	4	mV
Average Offset Voltage Drift	Full	-	3	-	-	3	-	$\mu\text{V}/^{\circ}\text{C}$
Bias Current	+25°C	-	100	250	-	100	250	nA
	Full	-	-	400	-	-	400	nA
Offset Current	+25°C	-	5	50	-	5	50	nA
	Full	-	-	80	-	-	80	nA
Common Mode Range	+25°C	0 to 3	-	-	$\pm 10$	-	-	V
Differential Input Resistance	+25°C	-	1.5	-	-	1.5	-	MΩ
Input Noise Voltage ( $f = 1\text{kHz}$ )	+25°C	-	14.8	-	-	14.8	-	$\text{nV}/\sqrt{\text{Hz}}$
Input Noise Current ( $f = 1\text{kHz}$ )	+25°C	-	0.25	-	-	0.25	-	$\text{pA}/\sqrt{\text{Hz}}$
<b>TRANSFER CHARACTERISTICS</b>								
Large Signal Voltage Gain (Notes 2, 4)	+25°C	50k	100k	-	50k	100k	-	V/V
	Full	25k	50k	-	25k	50k	-	V/V
Common Mode Rejection Ratio (Note 7)	Full	80	105	-	80	105	-	dB
Bandwidth (Notes 2, 3)	+25°C	-	1.3	-	-	1.3	-	MHz
<b>OUTPUT CHARACTERISTICS</b>								
Output Voltage Swing (Notes 2, 10)	+25°C	1 to 3.2	0.7 to 3.5	-	$\pm 10$	$\pm 13$	-	V
	Full	1.2 to 2.9	0.9 to 3.2	-	$\pm 10$	$\pm 13$	-	V
Full Power Bandwidth (Notes 2, 4, 8)	+25°C	-	700	-	-	95	-	kHz
<b>TRANSIENT RESPONSE (Notes 2, 3)</b>								
Rise Time	+25°C	-	300	-	-	300	-	ns
Slew Rate (Note 6)	+25°C	2	4.5	-	4	6	-	$\text{V}/\mu\text{s}$
Settling Time (Note 5)	+25°C	-	5	-	-	5	-	$\mu\text{s}$
<b>POWER SUPPLY CHARACTERISTICS</b>								
Supply Current	+25°C	-	200	250	-	200	250	$\mu\text{A}/\text{Amp}$
	Full	-	-	275	-	-	275	$\mu\text{A}/\text{Amp}$
Power Supply Rejection Ratio (Note 9)	Full	80	105	-	80	105	-	dB

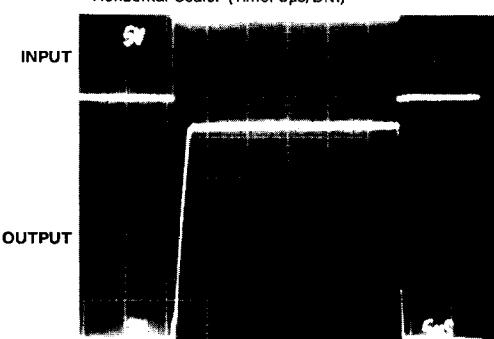
### NOTES:

1. Absolute maximum ratings are limiting values, applied individually beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied.
2.  $R_L = 10\text{k}\Omega$
3.  $C_L = 100\text{pF}$
4.  $V_O = 1.4$  to  $2.5\text{V}$  for  $V_{CC} = +5, 0\text{V}$ ;  $V_O = \pm 10\text{V}$  for  $V_{CC} = \pm 15\text{V}$ .
5. Settling Time is specified to 0.1% of final value for a  $3\text{V}$  output step and  $A_V = -1$ . For  $V_{CC} = +5, 0\text{V}$ ; output step =  $10\text{V}$  for  $V_{CC} = \pm 15\text{V}$ .
6. Maximum input slew rate =  $25\text{V}/\mu\text{s}$ .
7.  $V_{CM} = 0$  to  $3\text{V}$  for  $V_{CC} = +5, 0\text{V}$ ;  $V_{CM} = \pm 10\text{V}$  for  $V_{CC} = \pm 15\text{V}$
8. Full Power Bandwidth is guaranteed by equation:  

$$\text{Full Power Bandwidth} = \frac{\text{Slew Rate}}{2\pi V_{Peak}}$$
9.  $\Delta VS = +10\text{V}$  for  $V_{CC} = +5, 0\text{V}$ ;  $\Delta VS = \pm 5\text{V}$  for  $V_{CC} = \pm 15\text{V}$ .
10. For  $V_{CC} = +5, 0\text{V}$  terminate  $R_L$  at  $+2.5\text{V}$ .

**Test Circuits****SLEW RATE AND TRANSIENT RESPONSE TEST CIRCUIT****LARGE SIGNAL RESPONSE**

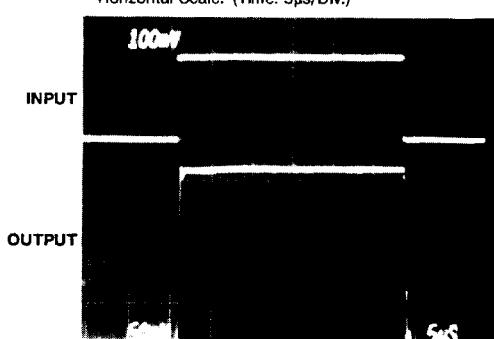
Vertical Scale: (Volts: Input = 5V/Div.)  
(Volts: Output = 2V/Div.)  
Horizontal Scale: (Time: 5μs/Div.)



+V<sub>SUPPLY</sub> = +15V, -V<sub>SUPPLY</sub> = -15V

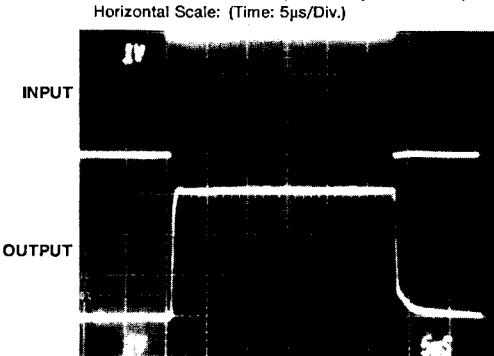
**SMALL SIGNAL RESPONSE**

Vertical Scale: (Volts: Input = 100mV/Div.)  
(Volts: Output = 50mV/Div.)  
Horizontal Scale: (Time: 5μs/Div.)



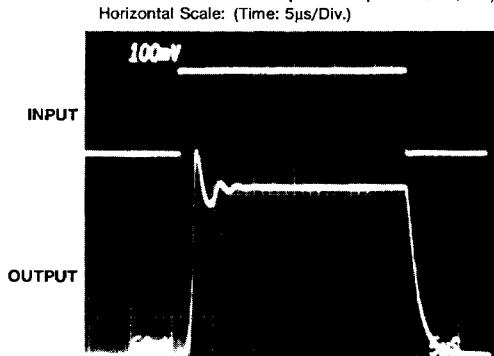
+V<sub>SUPPLY</sub> = +15V, -V<sub>SUPPLY</sub> = -15V

Vertical Scale: (Volts: Input = 1V/Div.)  
(Volts: Output = 1V/Div.)  
Horizontal Scale: (Time: 5μs/Div.)



+V<sub>SUPPLY</sub> = +5V, -V<sub>SUPPLY</sub> = 0V

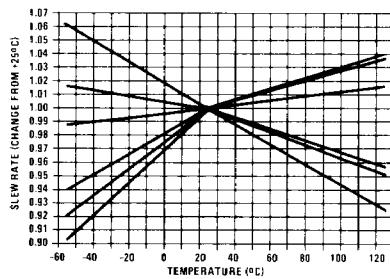
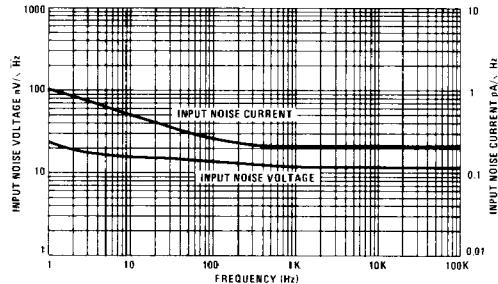
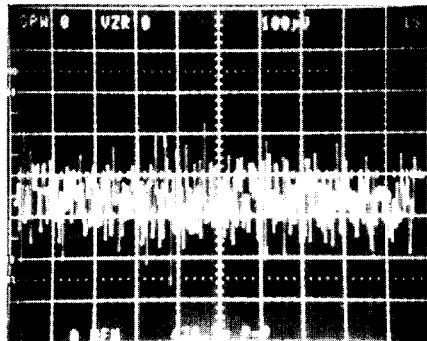
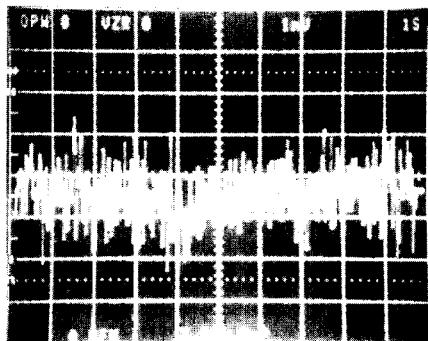
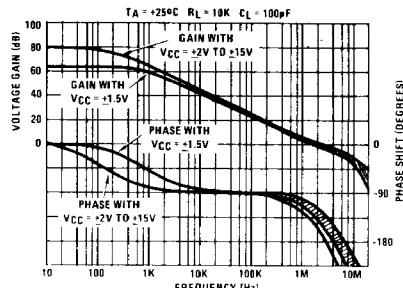
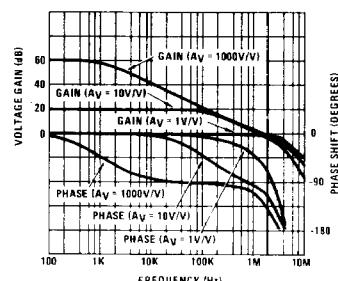
Vertical Scale: (Volts: Input = 100mV/Div.)  
(Volts: Output = 50mV/Div.)  
Horizontal Scale: (Time: 5μs/Div.)

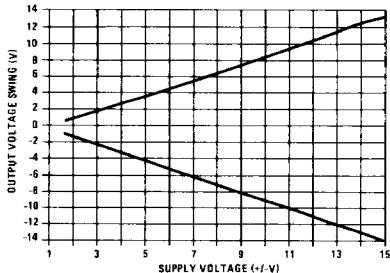
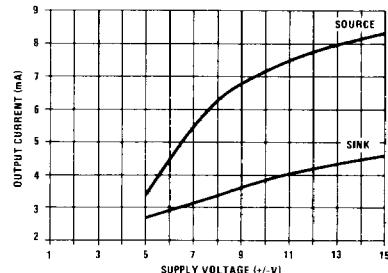
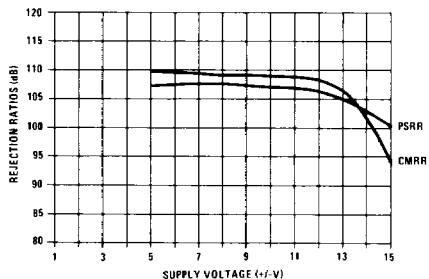
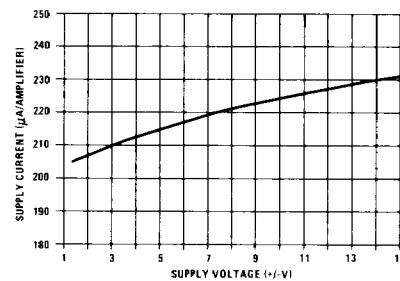
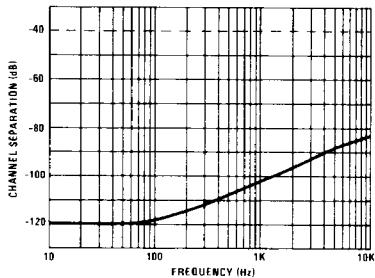
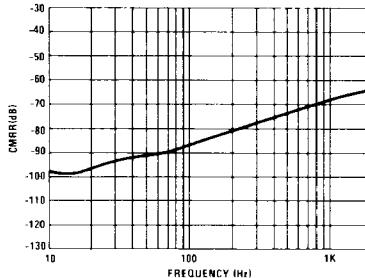


+V<sub>SUPPLY</sub> = +5V, -V<sub>SUPPLY</sub> = 0V

**Typical Characteristics****SLEW RATE vs. TEMPERATURE**

Normalized to Unity at +25°C, 6 Representative Units

**NOISE SPECTRAL DENSITY****PEAK-TO-PEAK NOISE 0.1Hz TO 10Hz**  
 $T_A = +25^\circ\text{C}$ ,  $A_V = 1000\text{V/V}$ Horizontal Scale: (1sec/div)  
Vertical Scale: (100μs/div)  
430nV<sub>p-p</sub> RTI**PEAK-TO-PEAK 0.1Hz TO 1MHz**  
 $T_A = +25^\circ\text{C}$ ,  $A_V = 1000\text{V/V}$ Horizontal Scale: (1sec/div)  
Vertical Scale: (1mV/div)  
3.70μV<sub>p-p</sub> RTI**FREQUENCY RESPONSE vs. SUPPLY VOLTAGE**  
 $T_A = +25^\circ\text{C}$ ,  $R_L = 10\text{k}$ ,  $C_L = 100\text{pF}$ **FREQUENCY RESPONSE AT VARIOUS GAINS**  
 $T_A = +25^\circ\text{C}$ ,  $V_{CC} = \pm 15\text{V}$ ,  $R_L = 10\text{k}$ ,  $C_L = 100\text{pF}$ 

**Typical Characteristics** (Continued)OUTPUT VOLTAGE SWING vs. SUPPLY VOLTAGE  
(+25°C)OUTPUT CURRENT vs. SUPPLY VOLTAGE  
(+25°C)CMMR, PSRR vs. SUPPLY VOLTAGE  
(+25°C)SUPPLY CURRENT vs. SUPPLY VOLTAGE  
Per Amplifier (+25°C)CHANNEL SEPARATION vs. FREQUENCY  
 $V_{CC} = \pm 15V$ ,  $T_A = +25^\circ C$ CMRR vs. FREQUENCY  
 $T_A = +25^\circ C$ ,  $V_{CC} = \pm 15V$ 

## Applications Information

### Independent Amplifiers

The HA-5152 dual op amp and the HA-5154 quad op amp consist of completely separate amplifier circuits. Unlike most duals and quads, these devices do not share a common bias network. Thus, one amplifier passing large, or noisy signals will have minimal effect on another channel carrying small, sensitive signals.

### Loading

Although the standard load is  $10\text{k}\Omega$ , the HA-515X is capable of driving resistive loads down to  $2\text{k}\Omega$  and capacitive loads beyond  $300\text{pF}$ .

### Input Stage

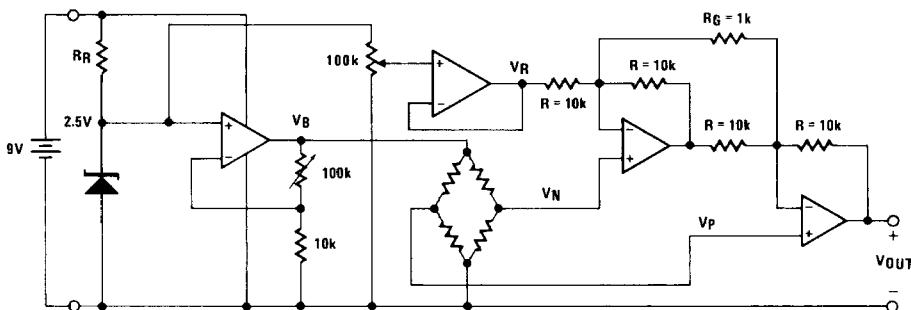
This amplifier uses a current amplifying input stage (see Application Note 544) and is not recommended for use in applications which involve large differential input voltages such as open-loop comparators. Most op amp applications

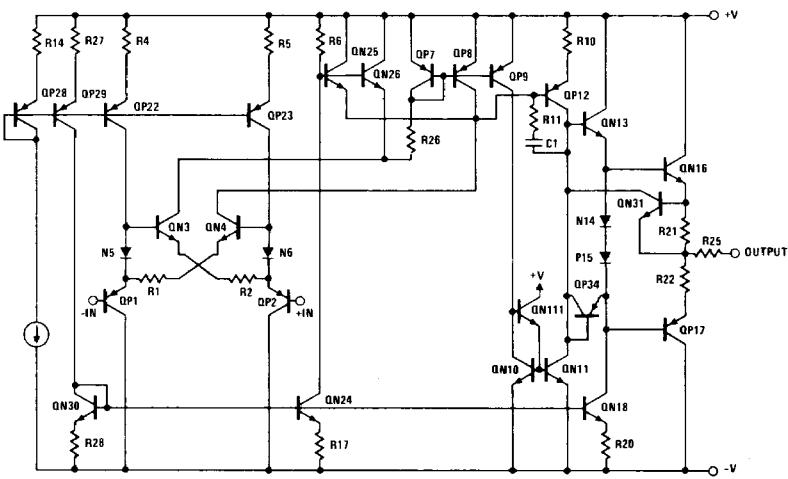
use feedback and keep the input terminals at approximately the same voltage. The HA-515X will perform well in these circuits as long as the input terminals see less than 7 volts differential.

### Typical Applications

The low power consumption of the HA-5154 makes it ideal for applications like battery-powered instrumentation where the bridge amplifier circuit below would be used. Choose a low-current zener voltage reference such as LM285Z-2.5 and select  $R_G$  accordingly. This circuit was evaluated using the resistor values shown and a laboratory voltage source for the 2.5V reference. With unmatched, off-the-shelf, 1% resistors, a gain accuracy of 1% to 2% can be expected. Temperature testing indicated a voltage offset tempco of less than  $100\mu\text{V}/^\circ\text{C}$  referred to output.

$$V_{\text{OUT}} = (V_P - V_N) \left[ 2\left(1 + \frac{R}{R_G}\right) \right] + V_R$$



*Schematic**Die Characteristics*

## Transistor Count

HA-5151.....	34
HA-5142.....	68
HA-5144.....	136
Substrate Potential* .....	V-

Process ..... Bipolar-DI

Thermal Constants ( $^{\circ}\text{C}/\text{W}$ )	$\theta_{ja}$	$\theta_{jc}$
HA1-5154 (-2, -5, -7)	101	33
HA1-5154 (883)	75	22
HA2-5151 (-2, -5, -7)	206	56
HA2-5151 (883)	168	50
HA2-5152 (-2, -5, -7)	184	50
HA2-5152 (883)	143	43
HA3-5151 (-5)	90	40
HA3-5152 (-5)	80	20
HA3-5154 (-5)	75	20
HA7-5151 (-2, -5, -7)	210	117
HA7-5151 (833)	90	40
HA7-5152 (-2, -5, -7)	177	92
HA7-5152 (883)	80	20

\*The substrate may be left floating (Insulating Die Mount) or it may be mounted on a conductor at V- potential.

NOTE: Consult Harris for LCC/PLCC information.

HARRIS SEMICOND SECTOR

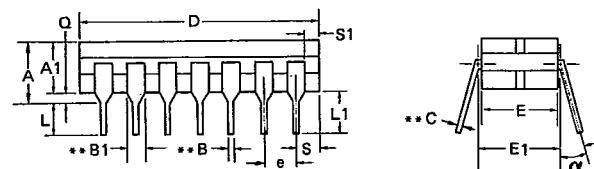
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## Package Configuration

A B C D E

.300 CERAMIC DUAL-IN-LINE

T-90-20

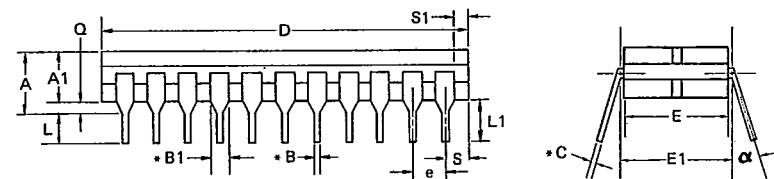


PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q	DIM. α
A	8 SSI	— .200	.140 .160	.016 .023	.050 .065	.008 .015	.375 .395	.245 .265	.290 .310	.100 BSC	.125 .150	.150 —	.005 .055	.015 —	.060 .150	.0° 15°
B1	14 MSI	— .200	.140 .170	.016 .023	.050 .065	.008 .015	.763 .785	.265 .285	.290 .310	.100 BSC	.125 .180	.150 —	.005 .098	.015 —	.060 .150	.0° 15°
B2	14 LSI	— .200	.140 .170	.016 .023	.050 .065	.008 .015	.753 .785	.285 .285	.300 .320	.100 BSC	.125 .180	.150 —	.005 .098	.015 —	.060 .150	.0° 15°
C1	16* MSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.753 .785	.265 .285	.290 .310	.100 BSC	.125 .180	.150 —	.005 .080	.015 —	.060 .150	.0° 15°
C2	16* LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.753 .785	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	.005 .080	.015 —	.060 .150	.0° 15°
D	18 LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.882 .915	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	.005 .098	.015 —	.060 .150	.0° 15°
E	20 LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.940 .970	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	.005 .080	.015 —	.060 .150	.0° 15°

\* End leads are half leads where B remains the same and B1 is  $\frac{0.035}{0.045}$   
\*\* Solder dip finish add +0.003 inches

F .400 CERAMIC DUAL-IN-LINE

G H .600 CERAMIC DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q	DIM. α
F .400	22 LSI	— .225	.150 .180	.016 .023	.050 .065	.008 .015	1.055 1.085	.375 .395	.395 .415	.100 BSC	.125 .180	.150 —	.005 .080	.015 —	.060 .150	.0° 15°
G .600	24 LSI	— .225	.150 .180	.016 .023	.050 .065	.008 .015	1.24 1.27	.515 .535	.595 .615	.100 BSC	.125 .180	.150 —	.005 .098	.015 —	.060 .150	.0° 15°
H .600	26 LSI	— .225	.160 .190	.016 .023	.050 .065	.008 .015	1.44 1.47	.515 .535	.595 .615	.100 BSC	.125 .180	.150 —	.005 .098	.015 —	.060 .150	.0° 15°

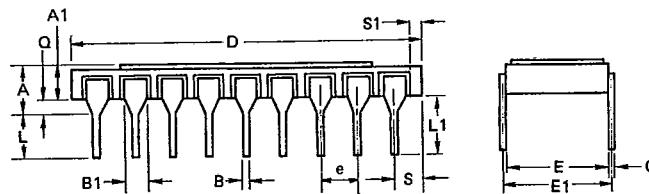
\* Solder dip finish add +0.003 inches.

NOTE: Dimensions are Min. Max. Dimensions are in inches.

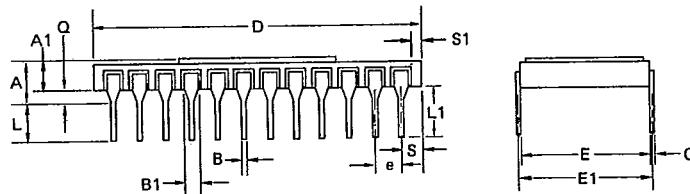
BSC means basic spacing between centerlines.

## Package Configuration

T-90-20

**I .300 SIDEBRAZE DUAL-IN-LINE**

PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q
I	18	— .200	.080 .110	.016 .023	.045 .060	.008 .015	.890 .910	.280 .300	.290 .310	.100 BSC	.125 .180	.150 —	— .098	.005 —	.025 .045

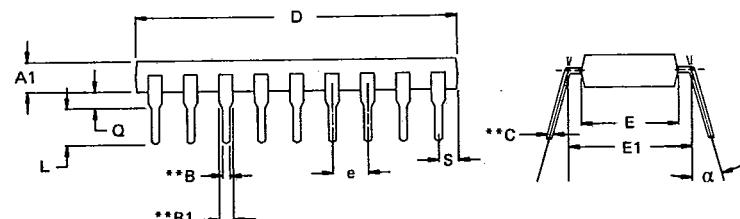
**J K L .600 SIDEBRAZE DUAL-IN-LINE**

PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q
J	24	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.185 1.215	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.040 .060
K	28	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.385 1.415	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.030 .060
L	40	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.980 2.020	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.040 .060

NOTE: Dimensions are Min. Max. Dimensions are in Inches.

BSC means basic spacing between centerlines.

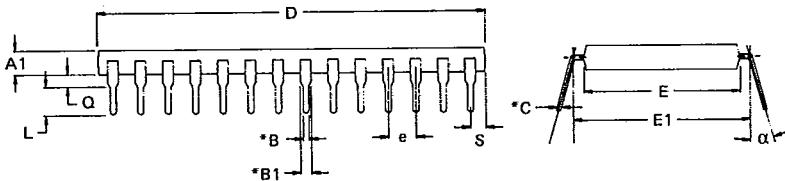
## M | N | O | P | Q .300 PLASTIC DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. S	DIM. Q	DIM. $\alpha$
M	8	.125 .140	.016 .023	.050 .070	.008 .015	.370 .390	.245 .265	.290 .310	.090 .110	.110 .150	.030 .050	.020 .040	0° 15°
'N	14	.125 .140	.016 .023	.050 .070	.008 .015	.750 .770	.245 .265	.280 .310	.080 .110	.110 .150	.030 .050	.020 .040	0° 15°
O	16*	.125 .140	.016 .023	.050 .070	.008 .015	.750 .770	.245 .265	.280 .310	.090 .110	.110 .150	.025 .035	.020 .040	0° 15°
P	18	.125 .140	.016 .023	.050 .070	.008 .015	.900 .920	.245 .265	.280 .310	.080 .110	.110 .150	.040 .060	.020 .040	0° 15°
Q	20	.130 .145	.016 .023	.050 .070	.008 .015	1.030 1.050	.250 .270	.290 .310	.090 .110	.110 .150	.060 .080	.020 .040	0° 15°

\* End leads are half leads where B remains the same and B1 is  $\frac{0.035}{0.045}$   
 \*\* Solder dip finish add 0.003 inches.

## R | S .600 PLASTIC DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. S	DIM. Q	DIM. $\alpha$
R	24	.145 .155	.016 .023	.050 .070	.008 .015	1.24 1.26	.540 .560	.590 .610	.090 .110	.110 .150	.045 .095	.020 .040	0° 15°
S	28	.145 .155	.016 .023	.050 .070	.008 .015	1.54 1.57	.540 .560	.590 .610	.090 .110	.110 .150	.110 .160	.020 .040	0° 15°

\* Solder dip finish add 0.003 inches.

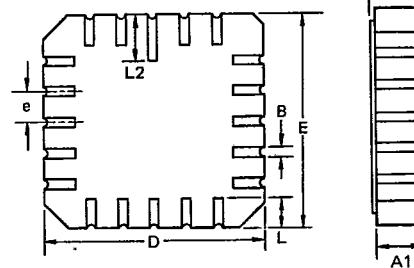
NOTE: Dimensions are  $\frac{\text{Min}}{\text{Max}}$ . Dimensions are in inches.

BSC means basic spacing between centerlines.

T-90-20

**T****.350 CERAMIC LEADLESS CHIP CARRIER\*****U****.450 CERAMIC LEADLESS CHIP CARRIER\*****V****.650 CERAMIC LEADLESS CHIP CARRIER\***

BOTTOM VIEW

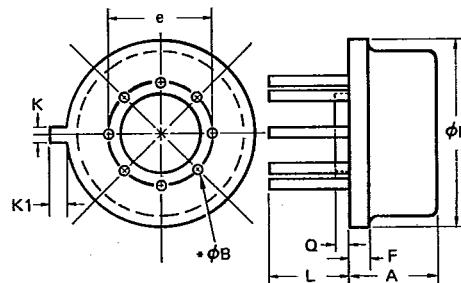


PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. D	DIM. E	DIM. e	DIM. L	DIM. L2
T	20 .350 SQ	.073 .089	.063 .077	.022 .028	.342 .358	.342 .358	.050 BSC	.045 .055	.075 .095
U	28 .450 SQ	.074 .088	.064 .076	.022 .028	.442 .458	.442 .458	.050 BSC	.045 .055	.075 .095
V	44 .650 SQ	.073 .089	.063 .077	.022 .028	.643 .662	.643 .662	.050 BSC	.045 .055	.075 .095

\* Solder dip finish for military parts conform to MIL-M-38510, Type A.

**W****TO-99 METAL CAN****X****TO-100 METAL CAN**

BOTTOM VIEW



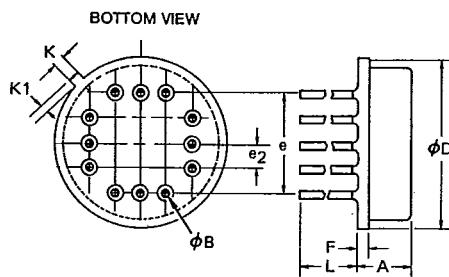
PKG. CODE	LEAD COUNT	DIM. A	DIM. φB	DIM. φD	DIM. e	DIM. F	DIM. K	DIM. K1	DIM. L	DIM. Q
W	8 TO-99	.165 .165	.016 .018	.345 .365	.190 .210	.020 .040	.028 .034	.028 .040	.505 .550	.015 .040
X	10 TO-100	.165 .165	.016 .018	.345 .365	.220 .240	.020 .040	.028 .034	.028 .040	.505 .550	.015 .040

\* Solder dip finish add +0.003 inches.

NOTE: Dimensions are <sub>Min.</sub>  
<sub>Max.</sub> Dimensions are in inches.

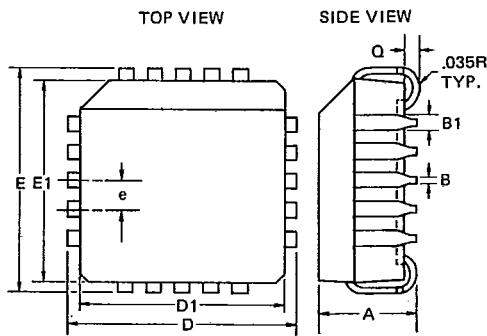
BSC means basic spacing between centerlines.

## Y TO-8 METAL CAN



PKG. CODE	LEAD COUNT	DIM. A	DIM. phi B	DIM. phi D	DIM. e	DIM. e2	DIM. F	DIM. K	DIM. K1	DIM. L
Y TO-8	12	.130 .150	.016 .021	.585 .615	.400 BSC	.100 BSC	.020 .040	.027 .034	.027 .045	.500 .550

## AA | AB | AC PLASTIC LEADED CHIP CARRIER



PKG. CODE	LEAD COUNT	DIM. A	DIM. B	DIM. B1	DIM. D/E	DIM. D1/E1	DIM. e	DIM. Q
AA	20	.165 .180	.013 .021	.026 .032	.385 .395	.350 .356	.050 BSC	.020 —
AB	28	.165 .180	.013 .021	.026 .032	.485 .495	.450 .456	.050 BSC	.020 —
AC	44	.165 .180	.013 .021	.026 .032	.685 .695	.650 .656	.050 BSC	.020 —

NOTE: Dimensions are <sub>Min.</sub> <sup>Max.</sup> Dimensions are in inches.

11-6

BSC means basic spacing between centerlines.